501923469 05/16/2012

PATENT ASSIGNMENT

Electronic Version v1.1 Stylesheet Version v1.1

| SUBMISSION TYPE: | NEW ASSIGNMENT |
|-----------------------|----------------|
| NATURE OF CONVEYANCE: | ASSIGNMENT |

CONVEYING PARTY DATA

| Name | Execution Date |
|-----------------|----------------|
| Hsu-Liang Hsiao | 03/14/2012 |
| Chun-Chiang Yen | 03/14/2012 |
| Guan-Fu Lu | 03/14/2012 |

RECEIVING PARTY DATA

| Name: | Centera Photonics Inc. |
|-----------------|---|
| Street Address: | 3F, No.6-3, Dusing Rd., Hsinchu Science Park, |
| City: | Hsinchu |
| State/Country: | TAIWAN |
| Postal Code: | 30078 |

PROPERTY NUMBERS Total: 1

| Property Type | Number |
|---------------------|----------|
| Application Number: | 13471460 |

CORRESPONDENCE DATA

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Correspondent Name: JIANQ CHYUN INTELLECTUAL PROPERTY OFFICE

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| ATTORNEY DOCKET NUMBER: | 41394-US-PA |
|-------------------------|-------------|
| NAME OF SUBMITTER: | Belinda Lee |

Total Attachments: 2

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> PATENT REEL: 028221 FRAME: 0497

1340,00

ASSIGNMENT

WHEREAS,

1. Hsu-Liang Hsiao

2. Chun-Chiang Yen

3. Guan-Fullu

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: WAFER-LEVEL PROCESS FOR FABRICATING PHOTOELECTRIC MODULES

[] Filed:

Serial No.

[x] Executed concurrently with the execution of this instrument

WHEREAS, Centera Photonics Inc.

of 3F. No.6-3, Dusing Rd., Hsinchu Science Park, Taiwan 30078, R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

| Signature: Hen - Ling Hein | Date: MW. 14, 2012 | / |
|--|---------------------|---|
| Sole or First Joint Inventor: Hsu-Liang Hsiao | | |
| Signature: | Date: Mir. 14, 2017 | |
| Signature: Guah - Zu Lu Third Joint Inventor (if any): Guan-Fu Lu | Date: Mar 14 vo1 | ٤ |

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